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Docket No.: S4-03P09159

IAP20 Rec'd PCT/PTO 01 FEB 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Jens Brandt, et al.
Filed : Concurrently herewith
Title : Electronic Unit and Method for Manufacturing an Electronic Unit

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner for Patents
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. 1.97(b)(1), the following patents and/or publications are submitted herewith cited to the Office:

U.S. Patent Application Publication No. 2002/0112870 A1 (Kobayashi, et al.), dated August 22, 2002;

U.S. Patent Application No. 6,222,733 B1 (Gammenthaler), dated April 24, 2001;

U.S. Patent Application No. 6,185,100 B1 (Bentz, et al.), dated February 6, 2001;

U.S. Patent Application No. 6,084,776 (Cuntz, et al.), dated July 4, 2000;

U.S. Patent Application No. 5,099,396 (Barz, et al.), dated March 24, 1992;

U.S. Patent Application 5,079,672 (Haubner, et al.), dated January 7, 1992;

European Patent Application EP 0 854 666 B1 (Lochbrunner, et al.), dated November 26, 2003, and English abstract thereof;

European Patent Application EP 0 540 071 A1 (Schwarz, et al.), dated May 5, 1993, corresponding to U.S. Patent Application 5,233.871;

German Published Non-Prosecuted Patent Application DE 197 01 731 A1 (Lochbrunner, et al.), dated July 23, 1998, and English abstract thereof;

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German Published Non-Prosecuted Patent Application DE 196 00 619 A1 (Bentz, et al.), dated July 17, 1997, corresponding to U.S. Patent Application No. 6,185,100, and English abstract thereof;

German Published Non-Prosecuted Patent Application DE 195 41 925 A1 (Bentz, et al.), dated May 15, 1997, and English abstract thereof;

German Published Non-Prosecuted Patent Application DE 195 28 632 A1 (Cuntz, et al), dated February 6, 1997, corresponding to U.S. Patent Application No. 6,084,776, and English abstract thereof;

„Handbuch der Leiterplattentechnik, Band 2: Neue Verfahren, Neue Technologien“ (Buck, et al.), pages 191-194 and 259-260.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant. As per the notice in 1273 OG 55 (August 5, 2003), no copies of any above-mentioned U.S. patents and U.S. patent application publications are submitted for any application filed after June 30, 2003.

Respectfully submitted,



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FORM PTO-1449 (SUBSTITUTE) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.97(b)(1))				Attorney Docket No.: S4-03P09159 Applicant No.: 666608 Concurrently herewith Applicant Jens Brandt, et al. Filing Date February 1, 2006 Group Art Unit			
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EXAMINER INITIALS	PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A	2002/0112870 A1	8/2002	Kobayashi, et al.		
	B	6,222,733 B1	4/2001	Gammenthaler		
	C	6,185,100 B1	2/2001	Bentz, et al.		
	D	6,084,776	7/2000	Cuntz, et al.		
	E	5,099,396	3/1992	Barz, et al.		
	F	5,079,672	1/1992	Haubner, et al.		
	G					
	H					
	I					

FOREIGN PATENT DOCUMENT							
DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES	TRANSL. NO	
J	EP 0 854 666 B1	11/2003	Europe				
K	EP 0 540 071 A1	5/1993	Europe				
L	DE 197 01 731 A1	7/1998	Germany				
M	DE 196 00 619 A1	7/1997	Germany				
N	DE 195 41 925 A1	5/1997	Germany				
O	DE 195 28 632 A1	2/1997	Germany				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)	
	„Handbuch der Leiterplattentechnik, Band 2: Neue Verfahren, Neue Technologien“ (Buck, et al.), pages 191-194 and 259-260.

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.